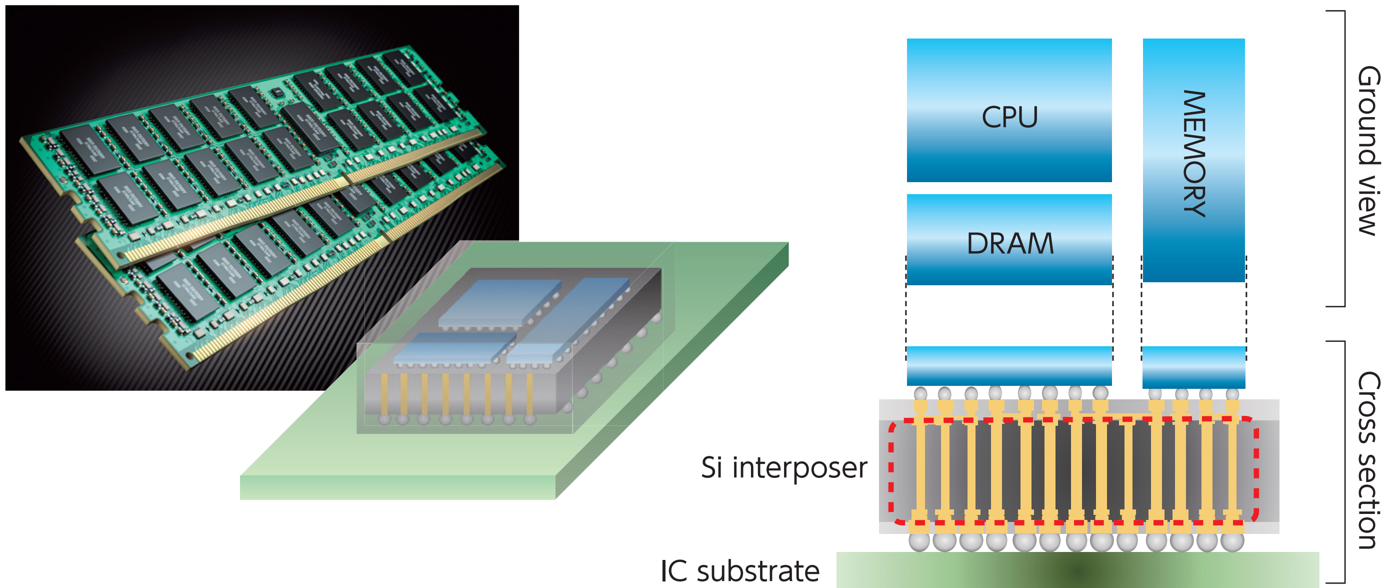
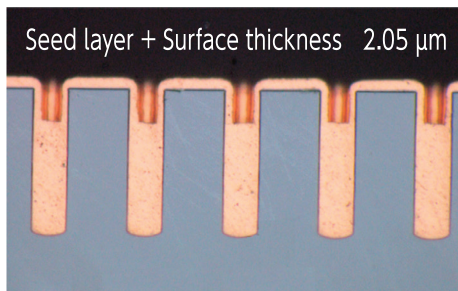
Acid copper plating additive to silicon interposer for high aspect ratio filling

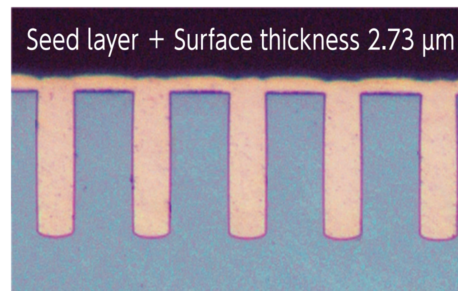
TORYZA LCN SV



High aspect filling by small thickness



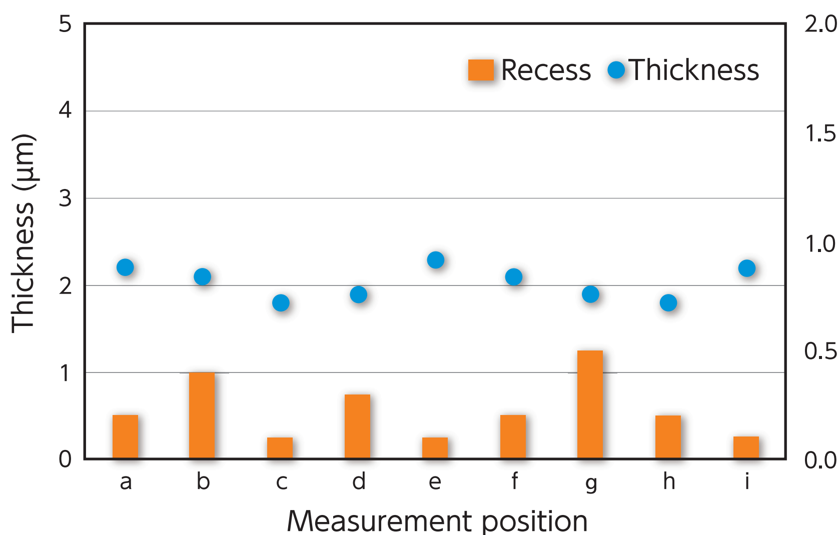
Plating time : 15 min



Plating time : 30 min

Current density: 0.2 A/dm² aperture diameter: 7 µm via depth: 25 µm

Excellent in filling performance into TGV



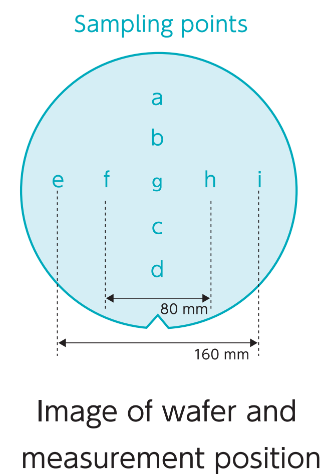


Image of wafer and measurement position